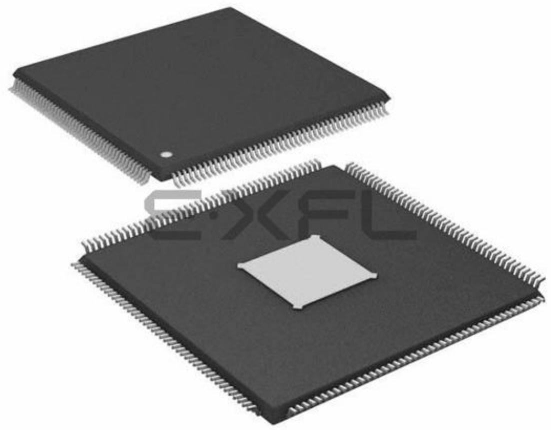

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® microAptiv™
Core Size	32-Bit Single-Core
Speed	200MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, LINbus, PMP, SPI, SQI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, HLVD, I²S, POR, PWM, WDT
Number of I/O	120
Program Memory Size	2MB (2M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	640K x 8
Voltage - Supply (Vcc/Vdd)	1.7V ~ 3.6V
Data Converters	A/D 45x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	176-LQFP Exposed Pad
Supplier Device Package	176-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mz2064dab176-i-2j

TABLE 7: PIN NAMES FOR 288-PIN DEVICES

288-PIN LFBGA (BOTTOM VIEW)

A1 V1

N6

PIC32MZ1025DAA288
PIC32MZ1025DAB288
PIC32MZ1064DAA288
PIC32MZ1064DAB288
PIC32MZ2025DAA288
PIC32MZ2025DAB288
PIC32MZ2064DAA288
PIC32MZ2064DAB288

F6

N13

F13

V18

A18

Polarity Indicator

Ball/Pin Number	Full Pin Name	Ball/Pin Number	Full Pin Name
A1	No Connect	B17	AN2/C1INB/RB4
A2	$\overline{\text{DDRUDQS}}$	B18	EBIA5/AN7/PMA5/RA5
A3	DDRDM1	C1	DDRDQ8
A4	D-	C2	DDRDQ15
A5	VSS	C3	DDRDQ9
A6	INT0/RH14	C4	VUSB3V3
A7	RPF2/SDA3/RF2	C5	VBUS
A8	AN21/RG15	C6	USBID
A9	AN14/C1IND/SCK2/RG6	C7	VSS
A10	TDI/AN17/SCK5/RF13	C8	No Connect
A11	TDO/AN31/RPF12/RF12	C9	AN30/C2IND/RPG8/SCL4/RG8
A12	EBID5/AN12/RPC1/PMD5/RC1	C10	AN25/RPE8/RE8
A13	$\overline{\text{EBIOE}}$/AN19/RPC4/PMRD/RC4	C11	EBID6/AN16/PMD6/RE6
A14	PGEC1/AN9/RPB1/CTED1/RB1	C12	No Connect
A15	EBID10/AN4/RPB8/PMD10/RB8	C13	EBID12/AN10/RPC2/PMD12/RC2
A16	AN8/RPB3/RB3	C14	AN49/RB11
A17	VREF-/CVREF-/AN27/RA9	C15	VREF+/CVREF+/AN28/RA10
A18	No Connect	C16	VDDIO
B1	No Connect	C17	AN1/C2INB/RPB2/RB2
B2	DDRUDQS	C18	AN6/RB12
B3	DDRDQ14	D1	DDRDQ13
B4	D+	D2	DDRDQ10
B5	VSS	D3	VSS1V8
B6	EBID4/AN18/PMD4/RE4	D4	TMS/$\overline{\text{SDCD}}$/RA0
B7	EBID0/PMD0/RE0	D5	VUSB3V3
B8	AN20/RH4	D6	No Connect
B9	EBIA2/AN23/C2INC/RPG9/PMA2/RG9	D7	VDDCORE
B10	AN26/RPE9/RE9	D8	EBID1/AN39/PMD1/RE1
B11	EBID7/AN15/PMD7/RE7	D9	AN13/C1INC/RPG7/SDA4/RG7
B12	No Connect	D10	VSS
B13	$\overline{\text{EBIWE}}$/AN34/RPC3/PMWR/RC3	D11	VSS
B14	PGEC2/RPB6/RB6	D12	VSS
B15	AN48/CTPLS/RB13	D13	VSS
B16	AN3/C2INA/RPB15/OCFB/RB15	D14	VDDCORE

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 and Table 4 for the available peripherals and **12.4 "Peripheral Pin Select (PPS)"** for restrictions.

2: Every I/O port pin (RAx-RKx) can be used as a change notification pin (CNAx-CNKx). See **12.0 "I/O Ports"** for more information.

3: Shaded pins are 5V tolerant.

4: This pin must be tied to Vss through a 20k Ω resistor when DDR is not connected in the system.

5: This pin is a No Connect when DDR is not connected in the system.

6: These pins are restricted to input functions only.

TABLE 1-22: DDR2 SDRAM CONTROLLER PINOUT I/O DESCRIPTIONS

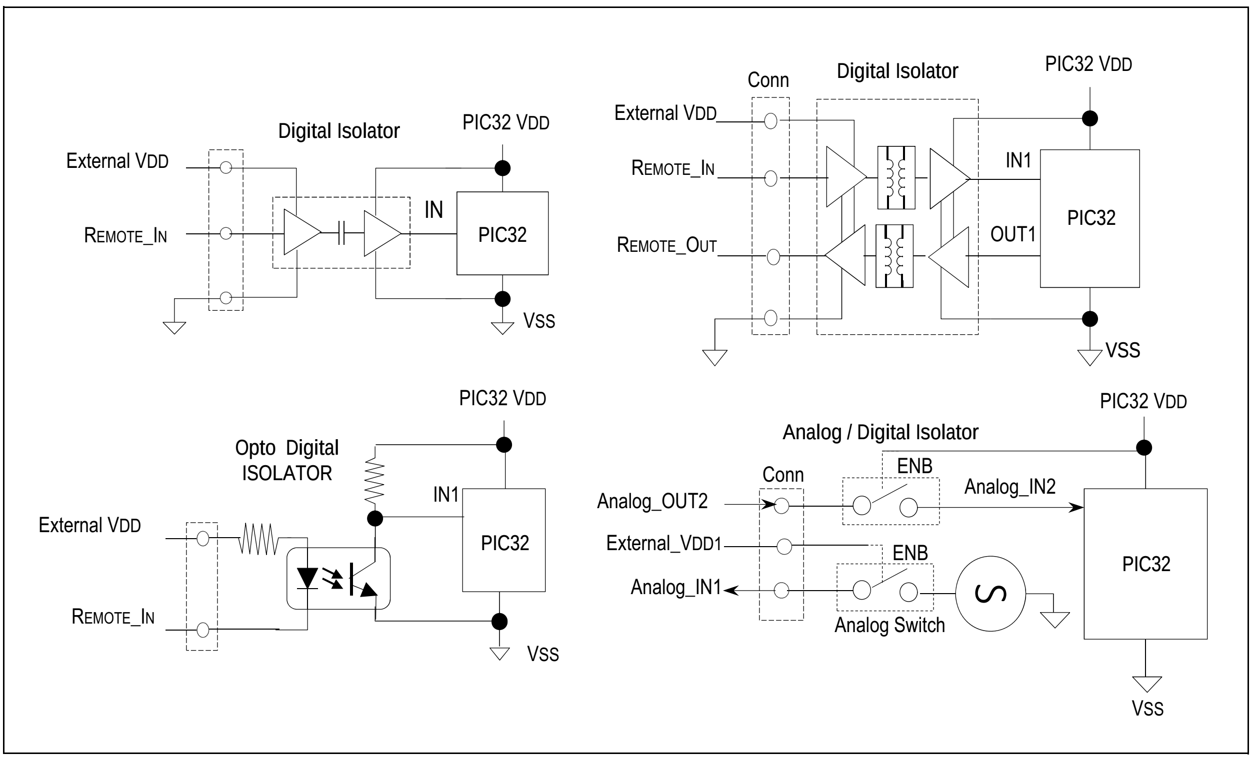
Pin Name	Pin Number			Pin Type	Buffer Type	Description
	169-pin LFBGA	176-pin LQFP	288-pin LFBGA			
DDR2 SDRAM Controller						
DDRCK	DDR Internal to the Package	DDR Internal to the Package	K2	O	SSTL	Differential Clocks
$\overline{\text{DDRCK}}$			K1	O	SSTL	
DDRCKE			L2	O	SSTL	Clock Enable
$\overline{\text{DDRCS0}}$			N2	O	SSTL	Chip Select 0
$\overline{\text{DDRRAS}}$			M1	O	SSTL	Row Address Strobe
$\overline{\text{DDRCAS}}$			P2	O	SSTL	Column Address Strobe
$\overline{\text{DDRWE}}$			L1	O	SSTL	Write Enable Strobe
DDRLDM			G3	O	SSTL	Lower Data Byte Mask
DDRUDM			A3	O	SSTL	Upper Data Byte Mask
DDRODT			N1	O	SSTL	On-Die Termination
DDRLDQS			E1	I/O	SSTL	Lower Data Byte Qualifier Strobes (Differential)
$\overline{\text{DDRLDQS}}$			E2	I/O	SSTL	
DDRUDQS			B2	I/O	SSTL	Upper Data Byte Qualifier Strobes (Differential)
$\overline{\text{DDRUDQS}}$			A2	I/O	SSTL	
DDRBA0			M2	O	SSTL	Bank Address Select 0
DDRBA1			M3	O	SSTL	Bank Address Select 1
DDRBA2			U4	O	SSTL	Bank Address Select 2
DDRA0			R1	O	SSTL	DDR2 Address Bus
DDRA1			L3	O	SSTL	
DDRA2			N3	O	SSTL	
DDRA3			R2	O	SSTL	
DDRA4			P3	O	SSTL	
DDRA5			T1	O	SSTL	
DDRA6			U1	O	SSTL	
DDRA7			T2	O	SSTL	
DDRA8			U2	O	SSTL	
DDRA9			R3	O	SSTL	
DDRA10			P1	O	SSTL	
DDRA11			V2	O	SSTL	
DDRA12			T3	O	SSTL	
DDRA13			U3	O	SSTL	
DDRA14			T4	O	SSTL	
DDRA15			V3	O	SSTL	

Legend: CMOS = CMOS-compatible input or output; ST = Schmitt Trigger input with CMOS levels; TTL = Transistor-transistor Logic input buffer; Analog = Analog input; O = Output; PPS = Peripheral Pin Select; P = Power; I = Input; SSTL = Stub Series Terminated Logic

TABLE 2-1: EXAMPLES OF DIGITAL/ ANALOG ISOLATORS WITH OPTIONAL LEVEL TRANSLATION

Example Digital/Analog Signal Isolation Circuits	Inductive Coupling	Capacitive Coupling	Opto Coupling	Analog/Digital Switch
ADuM7241 / 40 ARZ (1 Mbps)	X	—	—	—
ADuM7241 / 40 CRZ (25 Mbps)	X	—	—	—
ISO721	—	X	—	—
LTV-829S (2 Channel)	—	—	X	—
LTV-849S (4 Channel)	—	—	X	—
FSA266 / NC7WB66	—	—	—	X

FIGURE 2-6: EXAMPLE DIGITAL/ANALOG SIGNAL ISOLATION CIRCUITS



3.2 Architecture Overview

The MIPS32 microAptiv Microprocessor core in PIC32MZ DA family devices contains several logic blocks working together in parallel, providing an efficient high-performance computing engine. The following blocks are included with the core:

- Execution unit
- General Purpose Register (GPR)
- Multiply/Divide Unit (MDU)
- System control coprocessor (CP0)
- Memory Management Unit (MMU)
- Instruction/Data cache controllers
- Power Management
- Instructions and data caches
- microMIPS support
- Enhanced JTAG (EJTAG) controller

3.2.1 EXECUTION UNIT

The processor core execution unit implements a load/store architecture with single-cycle ALU operations (logical, shift, add, subtract) and an autonomous multiply/divide unit. The core contains thirty-two 32-bit General Purpose Registers (GPRs) used for integer operations and address calculation. Seven additional register file shadow sets (containing thirty-two registers) are added to minimize context switching overhead during interrupt/exception processing. The register file consists of two read ports and one write port and is fully bypassed to minimize operation latency in the pipeline.

The execution unit includes:

- 32-bit adder used for calculating the data address
- Address unit for calculating the next instruction address
- Logic for branch determination and branch target address calculation
- Load aligner
- Trap condition comparator
- Bypass multiplexers used to avoid stalls when executing instruction streams where data producing instructions are followed closely by consumers of their results
- Leading Zero/One detect unit for implementing the `CLZ` and `CLO` instructions
- Arithmetic Logic Unit (ALU) for performing arithmetic and bitwise logical operations
- Shifter and store aligner
- DSP ALU and logic block for performing DSP instructions, such as arithmetic/shift/compare operations

3.2.2 MULTIPLY/DIVIDE UNIT (MDU)

The processor core includes a Multiply/Divide Unit (MDU) that contains a separate pipeline for multiply and divide operations, and DSP ASE multiply instructions. This pipeline operates in parallel with the Integer Unit (IU) pipeline and does not stall when the IU pipeline stalls. This allows MDU operations to be partially masked by system stalls and/or other integer unit instructions.

The high-performance MDU consists of a 32x32 booth recoded multiplier, four pairs of result/accumulation registers (HI and LO), a divide state machine, and the necessary multiplexers and control logic. The first number shown (‘32’ of 32x32) represents the *rs* operand. The second number (‘32’ of 32x32) represents the *rt* operand.

The MDU supports execution of one multiply or multiply-accumulate operation every clock cycle.

Divide operations are implemented with a simple 1-bit-per-clock iterative algorithm. An early-in detection checks the sign extension of the dividend (*rs*) operand. If *rs* is 8 bits wide, 23 iterations are skipped. For a 16-bit wide *rs*, 15 iterations are skipped and for a 24-bit wide *rs*, 7 iterations are skipped. Any attempt to issue a subsequent `MDU` instruction while a divide is still active causes an IU pipeline stall until the divide operation has completed.

Table 3-1 lists the repeat rate (peak issue rate of cycles until the operation can be reissued) and latency (number of cycles until a result is available) for the processor core multiply and divide instructions. The approximate latency and repeat rates are listed in terms of pipeline clocks.

TABLE 3-1: MIPS32 microAptiv MICROPROCESSOR CORE HIGH-PERFORMANCE INTEGER MULTIPLY/DIVIDE UNIT LATENCIES AND REPEAT RATES

Opcode	Operand Size (mul *rt*) (div *rs*)	Latency	Repeat Rate
`MULT/MULTU, MADD/MADDU, MSUB/MSUBU` (HI/LO destination)	16 bits	5	1
	32 bits	5	1
`MUL` (GPR destination)	16 bits	5	1
	32 bits	5	1
`DIV/DIVU`	8 bits	12/14	12/14
	16 bits	20/22	20/22
	24 bits	28/30	28/30
	32 bits	36/38	36/38

4.2 DDR2 SDRAM

Stacked DDR2 SDRAM memory devices support 32 MB of DDR2 SDRAM. Memory in these devices is organized as 4,194,304 x 4 banks x 16 bits. Refer to Figure 4-1 and Table 4-1 for the DDR2 SDRAM address ranges.

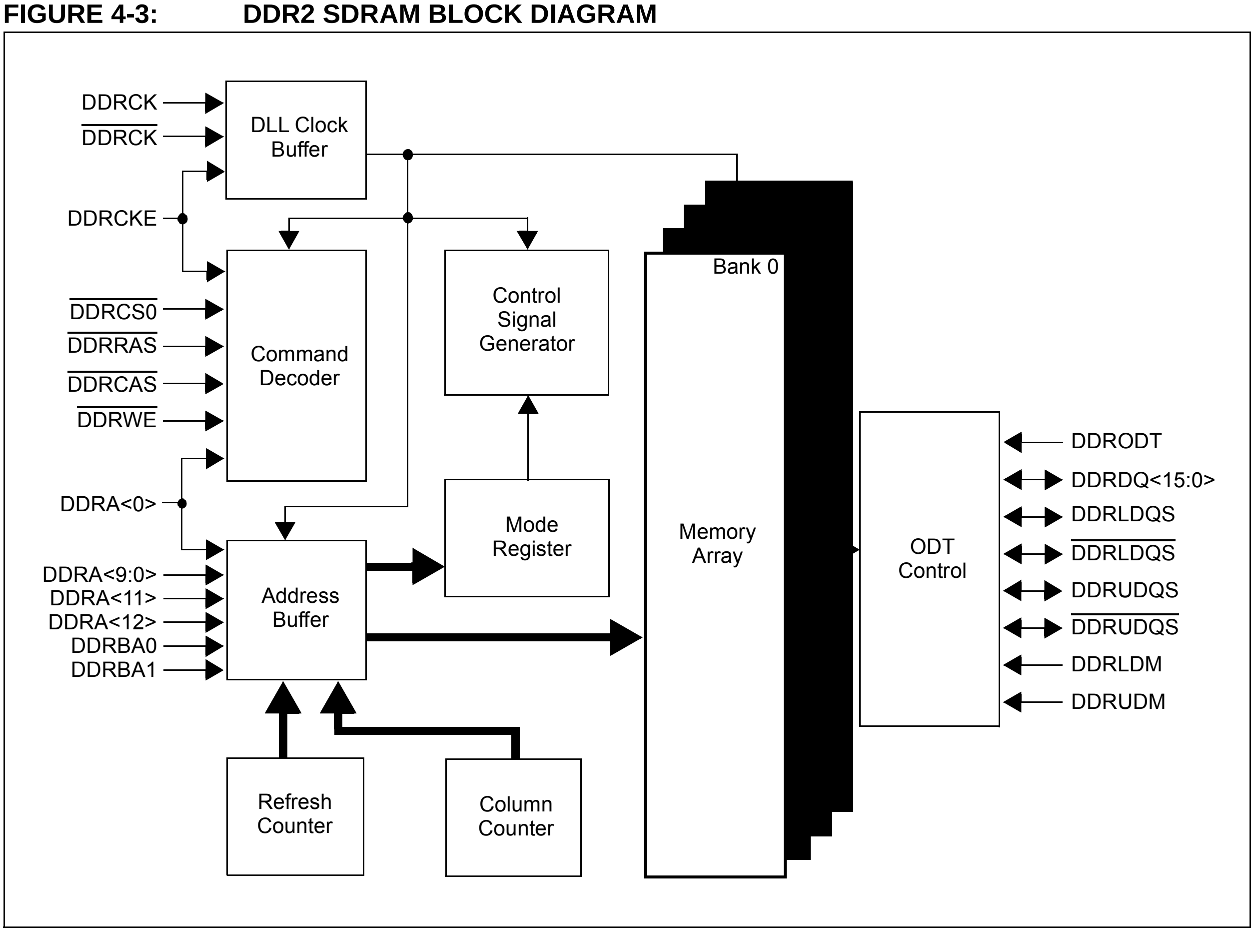
4.2.1 FEATURES

The DDR2 SDRAM includes the following features:

- Double Data Rate architecture: two data transfers per clock cycle
- CAS Latency: 3 and 4
- Burst Length: 8
- Bi-directional, differential data strobes (DDRUDQS, DDRLDQS and $\overline{\text{DDRUDQS}}$, $\overline{\text{DDRLDQS}}$) are transmitted / received with data
- Edge-aligned with Read data and center-aligned with Write data
- DLL aligns Data (DDRDQx) and Data Qualifier Strobe (DDRxDQS, $\overline{\text{DDRxDQS}}$) transitions with clock
- Differential clock inputs (DDRCK and /DDRCK)
- Data masks (DDRUDM, DDRLDM) for write data
- Commands entered on each positive DDRCK edge, data and data mask are referenced to both edges of DDRxDQS
- Posted CAS programmable additive latency supported to make command and data bus efficiency
- Read Latency = Additive Latency plus CAS Latency (RL = AL + CL)
- Off-Chip-Driver impedance adjustment (OCD) and On-Die-Termination (ODT) for better signal quality
- Auto-precharge operation for read and write bursts
- Auto Refresh and Self Refresh modes
- Precharged Power Down and Active Power Down
- Write Latency = Read Latency - 1 (WL = RL - 1)

Figure 4-3 provides a block diagram of the DDR2 SDRAM.

FIGURE 4-3: DDR2 SDRAM BLOCK DIAGRAM



4.3 Timing Parameters

Table 4-5 only applies to device variants with internal 32 MB DDR2 SDRAM. For device variants supporting external DDR2 SDRAM memory, refer to the vendor data sheet for timing parameters.

TABLE 4-5: TIMING PARAMETERS

Parameter	Description	Value	Units
tRFC	Auto-refresh Cycle Time	130	ns
tWR	Write Recovery Time	25	ns
tRP	Precharge-to-Active Command Delay Time	20	ns
tRCD	Active to Read/Write Command Delay Time	20	ns
tRRD	Row-to-Row (RAS to RAS) Command Delay Time	7.5	ns
tWTR	Write-to-Read Command Delay Time	15	ns
tRTP	Read-to-Precharge Command Delay Time	20	ns
tDLLK	DLL Lock Delay Time	200	Clock cycles
tRAS	Active to Precharge Minimum Command Delay Time	40	ns
tRC	Row Cycle Time	110	ns
tFAW	Four Bank Activation Window	35	ns
tMRD	Mode Register Set Command Cycle Delay	4	Clock cycles
tXP	Power Down Exit Delay	6	Clock cycles
tCKE	Power Down Minimum Delay	6	Clock cycles
RL	CAS Latency	4	Clock cycles
tRFI	Average Periodic Refresh Interval	7.8	µs
WL	Write Latency	3	Clock cycles
BL	Burst Length (in cycles)	8	Clock cycles

4.4 System Bus Arbitration

Note: The System Bus interconnect implements one or more instantiations of the SonicsSX® interconnect from Sonics, Inc. This document contains materials that are (c) 2003-2015 Sonics, Inc., and that constitute proprietary information of Sonics, Inc. SonicsSX is a registered trademark of Sonics, Inc. All such materials and trademarks are used under license from Sonics, Inc.

As shown in the PIC32MZ DA Family Block Diagram (see Figure 1-1), there are multiple initiator modules (I1 through I14) in the system that can access various target modules (T1 through T23). Table 4-6 illustrates which initiator can access which target. The System Bus supports simultaneous access to targets by initiators, so long as the initiators are accessing different targets. The System Bus will perform arbitration if multiple initiators attempt to access the same target.

REGISTER 4-5: SBFLAG3: SYSTEM BUS STATUS FLAG REGISTER 3

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
	—	—	—	—	—	—	T0PGV3(1)	T16PGV

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared

bit 31-2 **Unimplemented:** Read as ‘0’

bit 1 **T0PGV3:** Target 0 (System Bus 3) Permission Group Violation Status bit(1)
1 = Target 0 (System Bus 3) is reporting a Permission Group (PG) violation
0 = Target 0 (System Bus 3) is not reporting a PG violation

bit 0 **T16PGV:** Target 16 (DDR2 Target 3 and Target 4) Permission Group Violation Status bit
1 = Target 16 is reporting a Permission Group (PG) violation
0 = Target 16 is not reporting a PG violation

Note 1: System Bus 3 represents an internal sub-system element and should be treated as a general System Bus violation.

Note: All errors are cleared at the source (i.e., SBTxELOG1, SBTxELOG2, SBTxECLRS, or SBTxECLRM registers).

TABLE 11-1: USB REGISTER MAP 1 (CONTINUED)

Virtual Address	Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
3340	USB DPBFD	31:16	—	—	—	—	—	—	—	—	EP7TXD	EP6TXD	EP5TXD	EP4TXD	EP3TXD	EP2TXD	EP1TXD	—	0000
		15:0	—	—	—	—	—	—	—	—	EP7RXD	EP6RXD	EP5RXD	EP4RXD	EP3RXD	EP2RXD	EP1RXD	—	0000
3344	USB TMCON1	31:16	THHSRTN<15:0>																05E6
		15:0	TUCH<15:0>																4074
3348	USB TMCON2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	THSBT<3:0>				0000
3360	USB LPMR1	31:16	—	—	LPM ERRIE	LPM RESIE	LPMACKIE	LPMNYIE	LPMSTIE	LPMTOIE	—	—	—	LPMNAK(1) —(2)	LPMEN<1:0> —(2)	 —(2)	LPMRES	LPMXMT	0000 0000
		15:0	ENDPOINT<3:0>				—	—	—	RMTWAK	HIRD<3:0>				LNKSTATE<3:0>				0000
3364	USB LMPR2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	LPMFADDR<6:0>							—	—	LPMERR(1) —(2)	LPMRES	LPMNC	LPMACK	LPMNY	LPMST	0000 0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Device mode.

2: Host mode.

3: Definition for Endpoint 0 (ENDPOINT<3:0> (USBCSR<19:16>) = 0).

4: Definition for Endpoints 1-7 (ENDPOINT<3:0> (USBCSR<19:16>) = 1 through 7).

TABLE 11-2: USB REGISTER MAP 2

Virtual Address	Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
4000	USB CRCON	31:16	—	—	—	—	—	USBIF	USBRF	USBWKUP	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	USB IDOVEN	USB IDVAL	PHYIDEN	VBUS MONEN	ASVAL MONEN	BSVAL MONEN	SEND MONEN	USBIE	USBRIE	USB WKUPEN	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

13.0 TIMER1

Note:	This data sheet summarizes the features of the PIC32MZ Graphics (DA) Family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 14. "Timers"** (DS60001105), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

PIC32MZ DA devices feature one synchronous/asynchronous 16-bit timer that can operate as a free-running interval timer for various timing applications and counting external events. This timer can also be used with the low-power Secondary Oscillator (SOSC) for real-time clock applications.

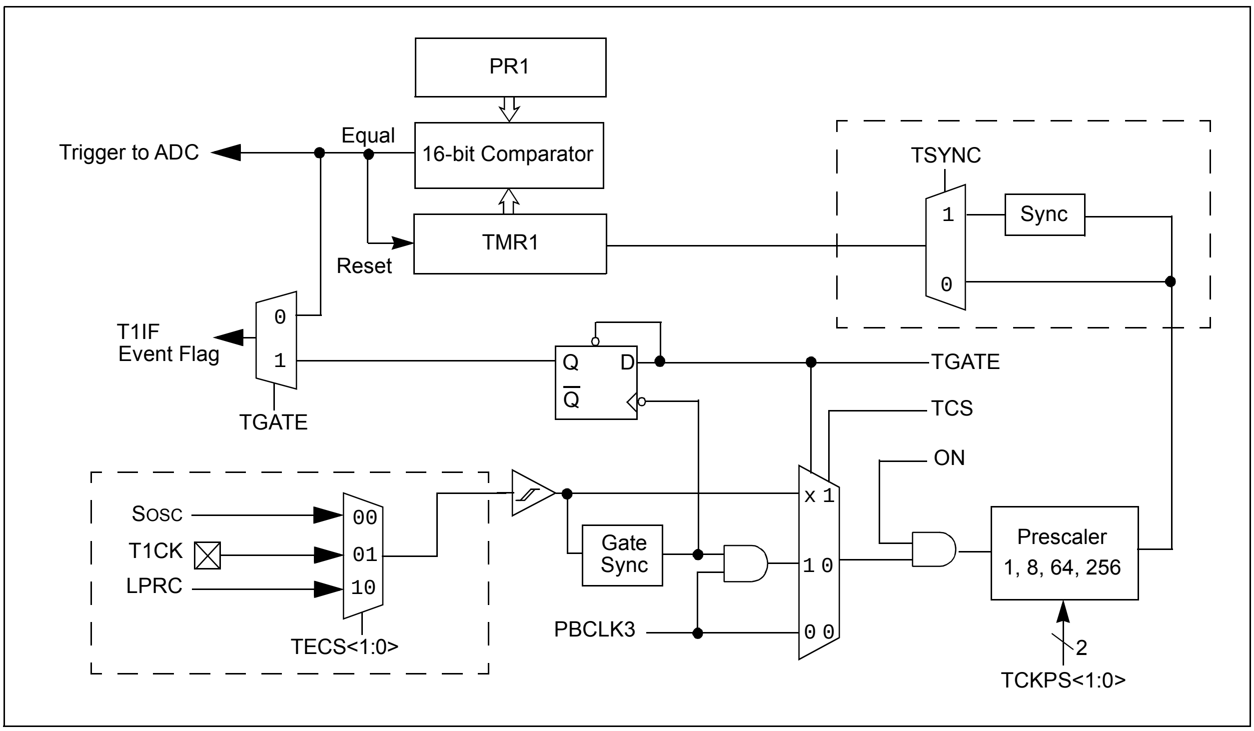
The following modes are supported by Timer1:

- Synchronous Internal Timer
- Synchronous Internal Gated Timer
- Synchronous External Timer
- Asynchronous External Timer

13.1 Additional Supported Features

- Selectable clock prescaler
- Timer operation during Sleep and Idle modes
- Fast bit manipulation using CLR, SET and INV registers
- Asynchronous mode can be used with the SOSC to function as a real-time clock
- ADC event trigger

FIGURE 13-1: TIMER1 BLOCK DIAGRAM



22.1 SQI Control Registers

TABLE 22-1: SERIAL QUADRATURE INTERFACE (SQI) REGISTER MAP

Virtual Address (BF8E_#)	Register Name	Bit Range	Bits 31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
2000	SQI1 XCON1	31:16	—	—	SDRCMD	DDRDATA	DDR DUMMY	DDR MODE	DDR ADDR	DDRCMD	DUMMYBYTES<2:0>			ADDRBYTES<2:0>			READOPCODE<7:6>		0000
		15:0	READOPCODE<5:0>						TYPEDATA<1:0>		TYPEDUMMY<1:0>		TYPEMODE<1:0>		TYPEADDR<1:0>		TYPECMD<1:0>		0000
2004	SQI1 XCON2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	DEVSEL<1:0>		MODEBYTES<1:0>		MODECODE<7:0>								0000
2008	SQI1CFG	31:16	—	—	—	—	—	—	CSEN<1:0>		SQIEN	—	DATAEN<1:0>		CON BUFRST	RXBUFST	TXBUFST	RESET	0000
		15:0	—	—	—	BURSTEN	—	HOLD	WP	—	—	—	LSBF	CPOL	CPHA	MODE<2:0>			0000
200C	SQI1CON	31:16	—	—	—	—	—	—	—	SCHECK	DDRMODE	DASSERT	DEVSEL<1:0>		LANEMODE<1:0>		CMDINIT<1:0>		0000
		15:0	TXRXCOUNT<15:0>																0000
2010	SQI1 CLKCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	CLKDIV<10:8>			0000
		15:0	CLKDIV<7:0>								—	—	—	—	—	—	STABLE	EN	0000
2014	SQI1 CMDTHR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	TXCMDTHR<5:0>						—	—	RXCMDTHR<5:0>						0000
2018	SQI1 INTTHR	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	TXINTTHR<5:0>						—	—	RXINTTHR<5:0>						0000
201C	SQI1 INTEN	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	DMAEIE	PKT COMPIE	BD DONEIE	CON THRIE	CON EMPTYIE	CON FULLIE	RX THRIE	RX FULLIE	RX EMPTYIE	TX THRIE	TX FULLIE	TX EMPTYIE	0000
2020	SQI1 INTSTAT	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	DMAEIF	PKT COMPIF	BD DONEIF	CON THRIF	CON EMPTYIF	CON FULLIF	RX THRIF	RX FULLIF	RX EMPTYIF	TX THRIF	TX FULLIF	TX EMPTYIF	0000
2024	SQI1 TXDATA	31:16	TXDATA<31:16>																0000
		15:0	TXDATA<15:0>																0000
2028	SQI1 RXDATA	31:16	RXDATA<31:16>																0000
		15:0	RXDATA<15:0>																0000
202C	SQI1 STAT1	31:16	—	—	—	—	—	—	—	—	—	—	TXBUFFREE<5:0>						0000
		15:0	—	—	—	—	—	—	—	—	—	—	RXBUFCNT<5:0>						0000
2030	SQI1 STAT2	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	CMDSTAT<1:0>		0000
		15:0	—	—	—	—	—	CONAVAIL<3:0>				SDID3	SDID2	SDID1	SDID0	—	RXUN	TXOV	00x0
2034	SQI1 BDCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	—	—	START	POLLEN	DMAEN	0000
2038	SQI1BD CURADD	31:16	BDCURRADDR<31:16>																0000
		15:0	BDCURRADDR<15:0>																0000
2040	SQI1BD BASEADD	31:16	BDADDR<31:16>																0000
		15:0	BDADDR<15:0>																0000

Figure 24-2 and Figure 24-3 illustrate typical receive and transmit timing for the UART module.

FIGURE 24-2: UART RECEPTION

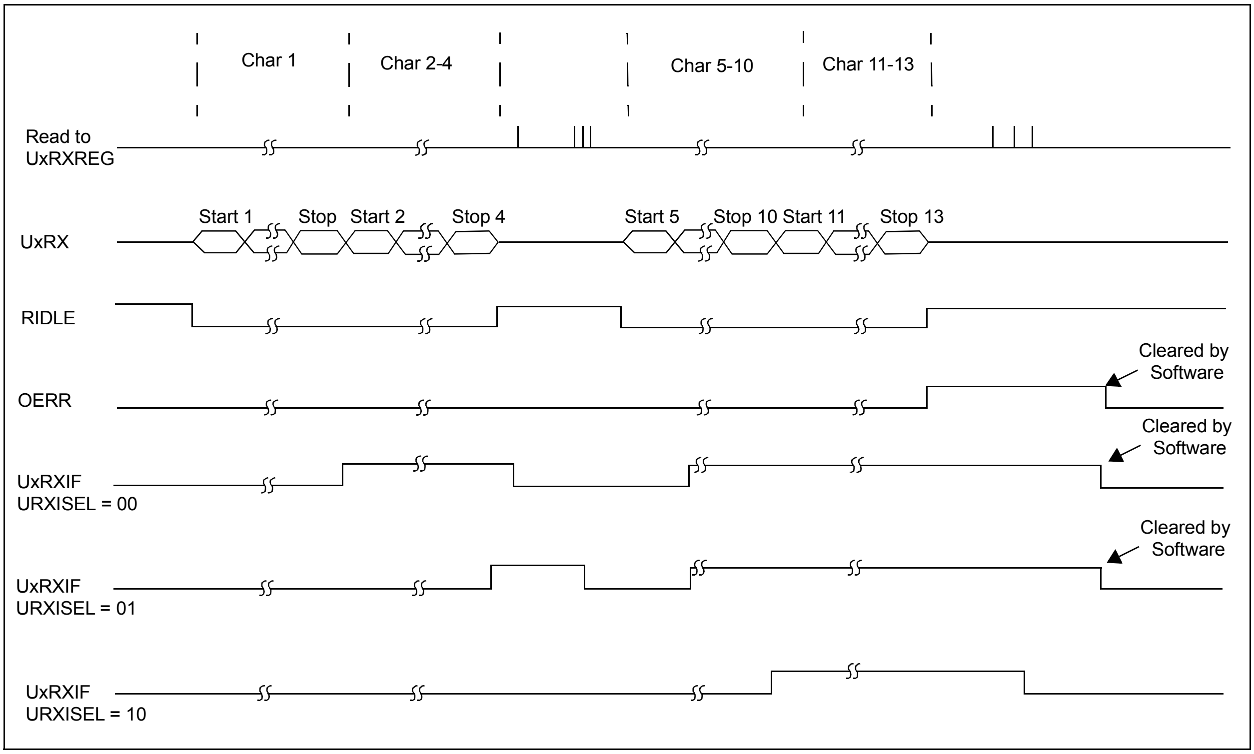
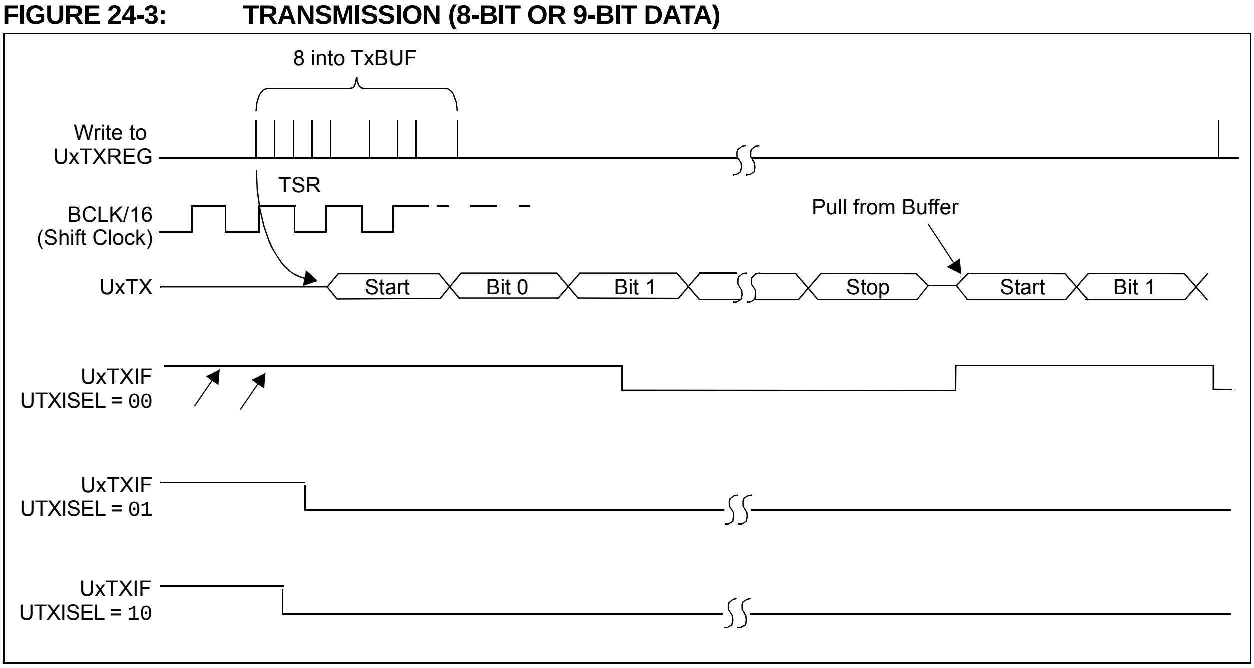


FIGURE 24-3: TRANSMISSION (8-BIT OR 9-BIT DATA)



REGISTER 26-5: EBISMCON: EXTERNAL BUS INTERFACE STATIC MEMORY CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-1	R/W-0
	SMDWIDTH2<2:0>			SMDWIDTH1<2:0>			SMDWIDTH0<2:1>	
7:0	R/W-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-1
	SMDWIDTH0<0>	—	—	—	—	—	—	SMRP

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15-13 **SMDWIDTH2<2:0>:** Static Memory Width for Register EBISMT2 bits

111 = Reserved
110 = Reserved
101 = Reserved
100 = 8 bits
011 = Reserved
010 = Reserved
001 = Reserved
000 = 16 bits

bit 12-10 **SMDWIDTH1<2:0>:** Static Memory Width for Register EBISMT1 bits

111 = Reserved
110 = Reserved
101 = Reserved
100 = 8 bits
011 = Reserved
010 = Reserved
001 = Reserved
000 = 16 bits

bit 9-7 **SMDWIDTH0<2:0>:** Static Memory Width for Register EBISMT0 bits

111 = Reserved
110 = Reserved
101 = Reserved
100 = 8 bits
011 = Reserved
010 = Reserved
001 = Reserved
000 = 16 bits

bit 6-1 **Unimplemented:** Read as '0'

bit 0 **SMRP:** Flash Reset/Power-down mode Select bit

After a Reset, the controller internally performs a power-down for Flash, and then sets this bit to '1'.

1 = Flash is taken out of Power-down mode
0 = Flash is forced into Power-down mode

REGISTER 27-9: CEHDLEN: CRYPTO ENGINE HEADER LENGTH REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	HDRLEN<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **HDRLEN<7:0>:** DMA Header Length bits
For every packet, skip this length of locations and start filling the data.

REGISTER 27-10: CETRLLEN: CRYPTO ENGINE TRAILER LENGTH REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
	TRLRLEN<7:0>							

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-8 **Unimplemented:** Read as '0'

bit 7-0 **TRLRLEN<7:0>:** DMA Trailer Length bits
For every packet, skip this length of locations at the end of the current packet and start putting the next packet.

FIGURE 27-3: FORMAT OF BD_SADDR

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31-24	BD_SAADDR<31:24>							
23-16	BD_SAADDR<23:16>							
15-8	BD_SAADDR<15:8>							
7-0	BD_SAADDR<7:0>							

bit 31-0 **BD_SAADDR<31:0>:** Security Association IP Session Address
The sessions' SA pointer has the keys and IV values.

FIGURE 27-4: FORMAT OF BD_SADDR

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31-24	BD_SAADDR<31:24>							
23-16	BD_SAADDR<23:16>							
15-8	BD_SAADDR<15:8>							
7-0	BD_SAADDR<7:0>							

bit 31-0 **BD_SAADDR<31:0>:** Security Association IP Session Address
The sessions' SA pointer has the keys and IV values.

FIGURE 27-5: FORMAT OF BD_SRCADDR

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31-24	BD_SCRADDR<31:24>							
23-16	BD_SCRADDR<23:16>							
15-8	BD_SCRADDR<15:8>							
7-0	BD_SCRADDR<7:0>							

bit 31-0 **BD_SCRADDR:** Buffer Source Address
The source address of the buffer that needs to be passed through the PE-CRDMA for encryption or authentication. This address must be on a 32-bit boundary.

REGISTER 30-3: CiINT: CAN INTERRUPT REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
	IVRIE	WAKIE	CERRIE	SERRIE	RBOVIE	—	—	—
23:16	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	MODIE	CTMRIE	RBIE	TBIE
15:8	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
	IVRIF	WAKIF	CERRIF	SERRIF(1)	RBOVIF	—	—	—
7:0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	—	—	MODIF	CTMRIF	RBIF	TBIF

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31 **IVRIE:** Invalid Message Received Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 30 **WAKIE:** CAN Bus Activity Wake-up Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 29 **CERRIE:** CAN Bus Error Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 28 **SERRIE:** System Error Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 27 **RBOVIE:** Receive Buffer Overflow Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 26-20 **Unimplemented:** Read as ‘0’

bit 19 **MODIE:** Mode Change Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 18 **CTMRIE:** CAN Timestamp Timer Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 17 **RBIE:** Receive Buffer Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 16 **TBIE:** Transmit Buffer Interrupt Enable bit
1 = Interrupt request enabled
0 = Interrupt request not enabled

bit 15 **IVRIF:** Invalid Message Received Interrupt Flag bit
1 = An invalid messages interrupt has occurred
0 = An invalid message interrupt has not occurred

Note 1: This bit can only be cleared by turning the CAN module Off and On by clearing or setting the ON bit (CiCON<15>).

REGISTER 30-20: CiFIFOCONn: CAN FIFO CONTROL REGISTER (n = 0 THROUGH 31)

bit 6 **TXABAT:** Message Aborted bit(2)
1 = Message was aborted
0 = Message completed successfully

bit 5 **TXLARB:** Message Lost Arbitration bit(3)
1 = Message lost arbitration while being sent
0 = Message did not loose arbitration while being sent

bit 4 **TXERR:** Error Detected During Transmission bit(3)
1 = A bus error occured while the message was being sent
0 = A bus error did not occur while the message was being sent

bit 3 **TXREQ:** Message Send Request
TXEN = 1: (FIFO configured as a Transmit FIFO)
Setting this bit to '1' requests sending a message.
The bit will automatically clear when all the messages queued in the FIFO are successfully sent
Clearing the bit to '0' while set ('1') will request a message abort.
TXEN = 0: (FIFO configured as a Receive FIFO)
This bit has no effect.

bit 2 **RTREN:** Auto RTR Enable bit
1 = When a remote transmit is received, TXREQ will be set
0 = When a remote transmit is received, TXREQ will be unaffected

bit 1-0 **TXPR<1:0>:** Message Transmit Priority bits
11 = Highest Message Priority
10 = High Intermediate Message Priority
01 = Low Intermediate Message Priority
00 = Lowest Message Priority

Note 1: These bits can only be modified when the CAN module is in Configuration mode (OPMOD<2:0> bits (CiCON<23:21>) = 100).
2: This bit is updated when a message completes (or aborts) or when the FIFO is reset.
3: This bit is reset on any read of this register or when the FIFO is reset.

REGISTER 38-5: DDRMEMCON: DDR MEMORY CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
	—	—	—	—	—	—	INITDN	STINIT

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-2 **Unimplemented:** Read as ‘0’

bit 1 **INITDN:** Memory Initialize Done bit

Set by software after memory initialization is completed to enable controller for regular operation.

1 = All commands have been issued; the controller is enabled for regular operation
0 = Controller not enabled for regular operation

bit 0 **STINIT:** Memory Initialize Start bit

Set by software after the memory initialization commands are loaded into the DDRCMD registers to start memory initialization.

1 = Start memory initialization
0 = Do not start memory initialization

REGISTER 38-24: DDRSCLSTART: DDL SELF CALIBRATION LOGIC START REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	R/W-0	R/W-0	U-0	W-0	U-0	R/W-0
	—	—	SCL PHCAL	SCL START	—	SCLEN	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
7:0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R-0	R-0
	—	—	—	—	—	—	SCLUB PASS(1)	SCLLB PASS(1)

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 31-30 **Unimplemented:** Write as ‘0’

bit 29 **SCLPHCAL:** Start Phase Self-calibration Logic bit
1 = Phase calibration is enabled
0 = Phase calibration is disabled

bit 28 **SCLSTART:** Start Self Calibration Logic bit
1 = Start self calibration
0 = Do not start self calibration

bit 27 **Unimplemented:** Write as ‘0’

bit 26 **SCLEN:** Self Calibration Logic Enable bit
1 = Enable dynamic self calibration logic
0 = Disable dynamic self calibration logic

Note: Enabling dynamic self calibration may impact performance.

bit 25-2 **Unimplemented:** Write as ‘0’

bit 1 **SCLUBPASS:** Self Calibration Logic Upper Data Byte Status bit(1)
1 = Self calibration logic for upper data byte passed
0 = Self calibration logic for upper data byte failed

bit 0 **SCLLBPASS:** Self Calibration Logic Lower Data Byte Status bit(1)
1 = Self calibration logic for lower data byte passed
0 = Self calibration logic for lower data byte failed

Note 1: This bit is set by hardware when the SCL process has passed and is complete.

44.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of the PIC32MZ DA electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the PIC32MZ DA devices are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions, above the parameters indicated in the operation listings of this specification, is not implied.

ABSOLUTE MAXIMUM RATINGS

(see Note1)

Ambient temperature under bias .... -40°C to +85°C
Storage temperature .... -65°C to +150°C
Voltage on V_{DDIO}, V_{DDCORE}, and V_{BAT} with respect to V_{SS} .... -0.3V to +4.0V
Voltage on V_{DDR1V8} pin with respect to V_{SS1V8} .... -0.5V to +1.98V
Voltage on DDR2 pins with respect to V_{SS1V8} .... -0.3V to (V_{DDR1V8} + 0.3V)
Voltage on any pin that is not 5V tolerant, with respect to V_{SS} **(Note 3)** .... -0.3V to (V_{DDIO} + 0.3V)
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DDIO} \geq 2.2V$ **(Note 3)** .... -0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to V_{SS} when $V_{DDIO} < 2.2V$ **(Note 3)** .... -0.3V to +3.6V
Voltage on D+ or D- pin with respect to V_{USB3V3} .... -0.3V to (V_{USB3V3} + 0.3V)
Voltage on V_{BUS} with respect to V_{SS} .... -0.3V to +5.5V
Maximum current out of V_{SS} pin(s) .... 200 mA
Maximum current into V_{DDIO} pin(s) **(Note 2)** .... 200 mA
Maximum current sunk/sourced by DDR2 pin .... 22 mA
Maximum current sunk/sourced by any 4x I/O pin **(Note 4)** .... 15 mA
Maximum current sunk/sourced by any 8x I/O pin **(Note 4)** .... 25 mA
Maximum current sunk/sourced by any 12x I/O pin **(Note 4)** .... 33 mA
Maximum current sunk by all ports **(Note 5)** .... 150 mA
Maximum current sourced by all ports **(Note 2, Note 5)** .... 150 mA

Note 1: Stresses above those listed under **"Absolute Maximum Ratings"** may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operation listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 44-2).

3: See the pin name tables (Table 5 through Table 7) for the 5V tolerant pins.

4: Characterized, but not tested. Refer to parameters DO10, DO20, and DO20a for the 4x, 8x, and 12x I/O pin lists.

5: Excludes DDR2 pins.

TABLE 44-42: I2Cx BUS DATA TIMING REQUIREMENTS (MASTER MODE) (CONTINUED)

AC CHARACTERISTICS				Standard Operating Conditions: VDDIO = 2.2V to 3.6V, VDDCORE = 1.7V to 1.9V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial			
Param. No.	**Symbol**	**Characteristics**		**Min.(1)**	**Max.**	**Units**	**Conditions**
IM21	TR:SCL	SDAx and SCLx Rise Time	100 kHz mode	—	1000	ns	CB is specified to be from 10 to 400 pF
			400 kHz mode	20 + 0.1 CB	300	ns	
			1 MHz mode **(Note 2)**	—	300	ns	
IM25	TSU:DAT	Data Input Setup Time	100 kHz mode	250	—	ns	—
			400 kHz mode	100	—	ns	
			1 MHz mode **(Note 2)**	100	—	ns	
IM26	THD:DAT	Data Input Hold Time	100 kHz mode	0	—	μs	—
			400 kHz mode	0	0.9	μs	
			1 MHz mode **(Note 2)**	0	0.3	μs	
IM30	TSU:STA	Start Condition Setup Time	100 kHz mode	TPBCLK2 * (BRG + 2)	—	μs	Only relevant for Repeated Start condition
			400 kHz mode	TPBCLK2 * (BRG + 2)	—	μs	
			1 MHz mode **(Note 2)**	TPBCLK2 * (BRG + 2)	—	μs	
IM31	THD:STA	Start Condition Hold Time	100 kHz mode	TPBCLK2 * (BRG + 2)	—	μs	After this period, the first clock pulse is generated
			400 kHz mode	TPBCLK2 * (BRG + 2)	—	μs	
			1 MHz mode **(Note 2)**	TPBCLK2 * (BRG + 2)	—	μs	
IM33	TSU:STO	Stop Condition Setup Time	100 kHz mode	TPBCLK2 * (BRG + 2)	—	μs	—
			400 kHz mode	TPBCLK2 * (BRG + 2)	—	μs	
			1 MHz mode **(Note 2)**	TPBCLK2 * (BRG + 2)	—	μs	
IM34	THD:STO	Stop Condition Hold Time	100 kHz mode	TPBCLK2 * (BRG + 2)	—	ns	—
			400 kHz mode	TPBCLK2 * (BRG + 2)	—	ns	
			1 MHz mode **(Note 2)**	TPBCLK2 * (BRG + 2)	—	ns	
IM40	TAA:SCL	Output Valid from Clock	100 kHz mode	—	3500	ns	—
			400 kHz mode	—	1000	ns	—
			1 MHz mode **(Note 2)**	—	350	ns	—
IM45	TBF:SDA	Bus Free Time	100 kHz mode	4.7	—	μs	The amount of time the bus must be free before a new transmission can start
			400 kHz mode	1.3	—	μs	
			1 MHz mode **(Note 2)**	0.5	—	μs	
IM50	CB	Bus Capacitive Loading		—	—	pF	See parameter DO58
IM51	TPGD	Pulse Gobbler Delay		52	312	ns	See **Note 3**

Note 1: BRG is the value of the I²C Baud Rate Generator.

2: Maximum pin capacitance = 10 pF for all I2Cx pins (for 1 MHz mode only).

3: The typical value for this parameter is 104 ns.